

# Step-up PWM DC/DC Converter

#### ❖ GENERAL DESCRIPTION

The AX5202 is high efficient step-up DC/DC converter. Large output current is possible having a built in internal N channel MOSFET, and using an external coil and diode.

The AX5202 can be operated at switching frequencies of 500 kHz allowing for easy filtering and low noise, the size of the external components can be reduced.

Output voltage is programmable with 1.0V of standard voltage supply internal, and using externally connected components, output voltage (FB) can be set up at will. The soft-start time can be programmed by outside capacitor; the function prevents overshoot at startup. Build inside Current limit, Thermal Shutdown and enable functions.

#### ❖ FEATURES

Input voltage: 3V to 16V

Output voltage: 3.3V to 23V

Duty ratio: 0% to 85% PWM control

Oscillation frequency: 500KHz.

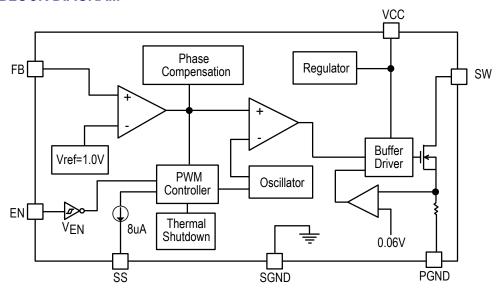
Enable and Thermal Shutdown function.

Internal Current limit.

Built-in N-channel MOSFET

SOP-8L with Exposed pad Pb-Free package.

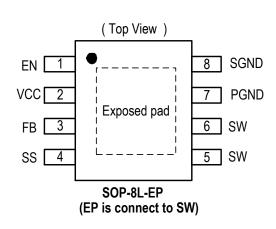
#### **❖ BLOCK DIAGRAM**





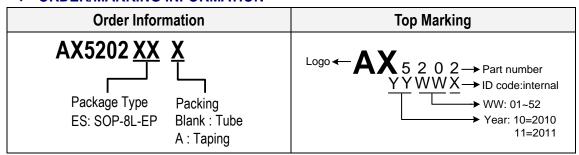
#### **❖ PIN ASSIGNMET**

The package of AX5202 is SOP-8L-EP; the pin assignment is given by:



Name	Description				
EN	Power-off pin H: normal operation(Step-up)				
	L: Step-up operation stopped				
VCC	IC power supply pin				
FB	Feedback pin				
SS	Soft-Start Pin.				
SW	Switch pin. Connect external inductor and diode here.				
PGND	Power Ground pin				
SGND	Signal Ground pin.				

#### ❖ ORDER/MARKING INFORMATION



## **❖ ABSOLUTE MAXIMUM RATINGS** (at T<sub>A</sub>=25°C)

Characteristics	Symbol	Rating	Unit
VCC Pin Voltage	Vcc	GND - 0.3 to GND + 18	V
Feedback Pin Voltage	$V_{FB}$	GND - 0.3 to 6	V
ON/OFF Pin Voltage	$V_{EN}$	GND - 0.3 to $V_{\text{CC}}$	V
Switch Pin Voltage	$V_{SW}$	GND - 0.3 to 25	V
SS Pin Voltage	V <sub>SS</sub>	GND - 0.3 to 6	V
Power Dissipation	PD	Internally limited	mW
Storage Temperature Range	T <sub>ST</sub>	-40 to +150	°C
Operating Junction Temperature	T <sub>OPJ</sub>	-20 to +125	°C
Thermal Resistance from Junction to case	θ <sub>JC</sub>	15	°C/W
Thermal Resistance from Junction to ambient	θја	40	°C/W

Note:  $\theta_{JA}$  is measured with the PCB copper area (connect to exposed pad) of approximately 1 in<sup>2</sup>(Multi-layer).

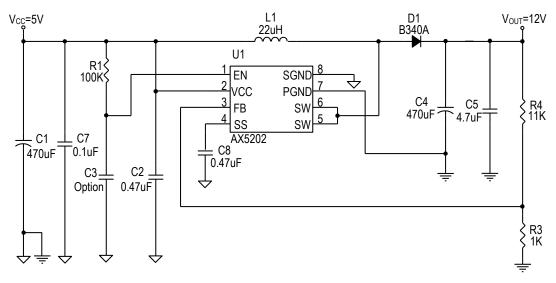
# **\* ELECTRICAL CHARACTERISTICS**

(V<sub>CC</sub> = 5V, V<sub>OUT</sub>=12V, T<sub>A</sub>=25°C, unless otherwise specified)

Characteristics	Symbol	Conditions		Min	Тур	Max	Units
Operating Supply Voltage	Vcc			3	-	16	٧
Output Voltage Range	V <sub>OUT</sub>			3.3	-	23	V
Feedback Voltage	$V_{FB}$	I <sub>OUT</sub> =0.1A		0.98	1.00	1.02	V
Feedback Bias Current	I <sub>FB</sub>	I <sub>OUT</sub> =0.1A		-	0.1	0.5	uA
Quiescent Current	Iccq	V <sub>FB</sub> =1.5V force	e driver off	-	4	6	mΑ
Shutdown Supply Current	I <sub>SD</sub>	V <sub>EN</sub> =0V		-	1	10	uA
Oscillation Frequency	Fosc	SW pin		400	500	600	KHz
Line Regulation		V <sub>CC</sub> =3~0.8*V <sub>C</sub>	DUT	-	1	-	%
Load Regulation		I <sub>OUT</sub> =50m~500	)mA	-	0.5	-	%
EN Pin Logic input threshold	V <sub>SH</sub>	High (regulator ON)		2.0	-	-	\ /
voltage	V <sub>SL</sub>	Low (regulator OFF)		-	-	0.8	V
EN Din Innut Cumant	I <sub>SH</sub>	V <sub>EN</sub> =2.5V (ON)		-	20	-	uA
EN Pin Input Current	I <sub>SL</sub>	V <sub>EN</sub> =0.3V (OFF)		-	-1	-	uA
SS pin Current	I <sub>SS</sub>			-	8	-	uA
Switching Current Limit	I <sub>LIM-sw</sub>			2.2	2.5	-	Α
Internal MOCEET D	В	V <sub>CC</sub> =5V		-	100	150	C
Internal MOSFET R <sub>DSON</sub>	R <sub>DSON</sub>	V <sub>CC</sub> =12V		-	70	100	mΩ
Efficiency	EFFI	V <sub>CC</sub> =5V V <sub>ОUT</sub> =12V	I <sub>OUT</sub> = 0.5A	-	90	-	%
Maximum Duty Cycle	DC <sub>MAX</sub>	V <sub>FB</sub> =0V		-	85	-	0/
Minimum Duty Cycle	DC <sub>MIN</sub>	V <sub>FB</sub> =1.5V		-	0	-	%
Thermal shutdown Temp	TSD			-	145	ı	ŝ



#### APPLICATION CIRCUIT



$$V_{OUT} = V_{FB} \times (1 + \frac{R4}{R3}), V_{FB} = 1.0V, R3 = 1K \sim 3K\Omega$$

#### **FUNCTION DESCRIPTIONS**

#### **PWM Control**

The AX5202 consists of DC/DC converters that employ a pulse-width modulation (PWM) system. In converters of the AX5202, the pulse width varies in a range from 0 to 85%, according to the load current. The ripple voltage produced by the switching can easily be removed through a filter because the switching frequency remains constant. Therefore, these converters provide a low-ripple power over broad ranges of input voltage and load current.

#### **Setting the Output Voltage**

Application circuit item shows the basic application circuit with AX5202 adjustable output version. The external resistor sets the output voltage according to the following equation:



$$\mathbf{V}_{out} = 1.0\mathbf{V} \times \left(1 + \frac{\mathbf{R4}}{\mathbf{R3}}\right)$$

Table 1 Resistor select for output voltage setting

V <sub>OUT</sub>	R3	R4
12V	1K	11K
15V	1.3K	18K
18V	1.3K	22K

#### Inductor Selection

For most designs, Low inductance values are physically smaller but require faster switching, which results in some efficiency loss. The inductor value can be derived from the following equation:

$$L = \frac{V_{IN} \times (V_{OUT} - V_{IN})}{V_{OUT} \times \Delta I_{L} \times f_{LX}}$$

Where is inductor Ripple Current. Large value inductors lower ripple current and small value inductors result in high ripple currents. Choose inductor ripple current approximately 15% of the maximum input current 1.6A, ΔI<sub>L</sub>=0.24A.

Table 2 Inductor select for output voltage setting (V<sub>CC</sub>=5V)

		•	U	0 (
Vout	9V	12V	15V	18V
L1 Value	18uH	22uH	25uH	33uH

The DC current rating of the inductor should be at least equal to the maximum load current plus half the ripple current to prevent core saturation (1.6A+0.12A).

#### Input Capacitor Selection

The input capacitor reduces the surge current drawn from the input and switching noise from the device. The input capacitor impedance at the switching frequency shall be less than input source impedance to prevent high frequency switching current passing to the input. A low ESR input capacitor sized for maximum RMS current must be used.

The capacitor voltage rating should be at least 1.5 times greater than the input voltage, and often much higher voltage ratings are needed to satisfy.

# **Output Capacitor Selection**

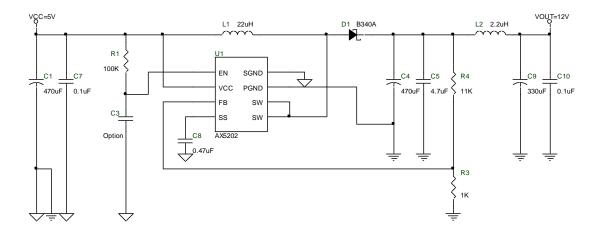
The output capacitor is required to keep the output voltage ripple small and to ensure regulation loop stability. The output capacitor must have low impedance at the switching frequency. A low ESR capacitor sized for maximum RMS current must be used. The low ESR requirements needed for low output ripple voltage.

The capacitor voltage rating should be at least 1.5 times greater than the input voltage, and often much higher voltage ratings are needed to satisfy.

### **Output Voltage Ripple**

Application circuit item shows the basic application circuit with AX5202. The output voltage ripple ( $V_{RIPPLE}$ ) very lager at high switch current( $I_{SW}$ =3A,  $V_{RIPPLE}$ =0.7V), external  $\pi$  filters can reduce output voltage ripple.

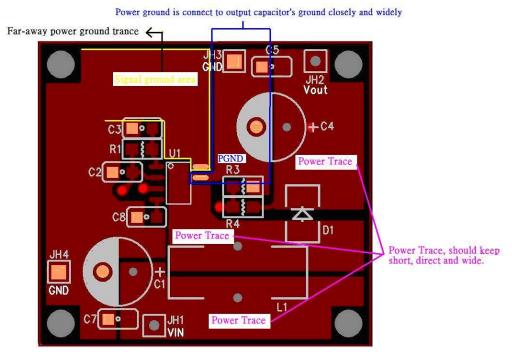
#### $\pi$ filters



#### Layout Guidance (please refer layout picture)

When laying out the PC board, the following suggestions should be taken to ensure proper operation of the AX5202. These items are also illustrated graphically in below.

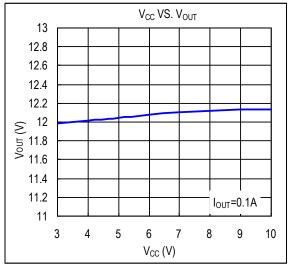
- 1. The power traces, including the Source trace, the Schottky and the C1 trace should be kept short, direct and wide to allow large current flow.
- 2. The power ground is keep C4's ground closed and far away signal ground.
- 3. The signal ground trance is distant from power ground trance.
- The exposed pad is connecting to SW trace closely and widely. (Reduce IC temperature)
- 5. Do not trace signal line under inductor.

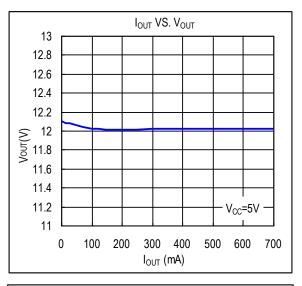


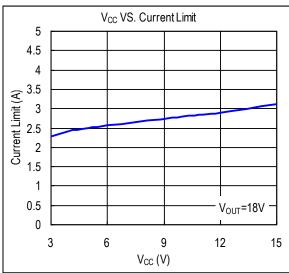
(AX5202 PCB Layout -Top View)

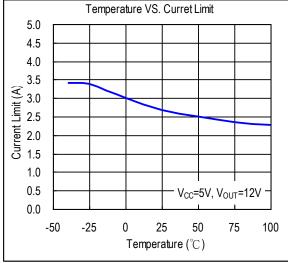


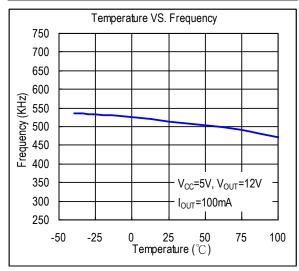
#### TYPICAL CHARACTERISTICS

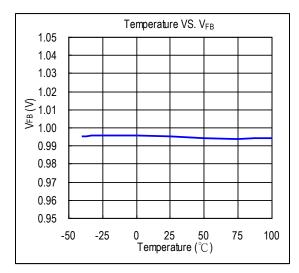








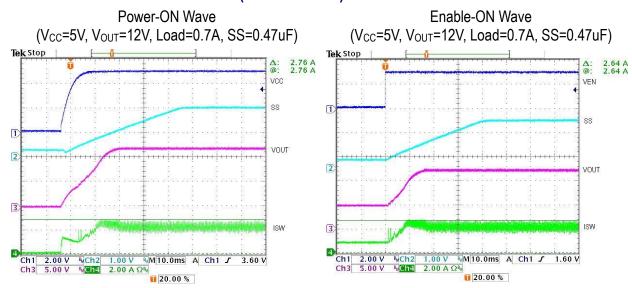




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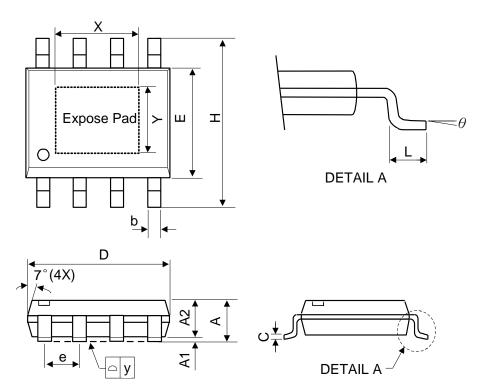


# **❖ TYPICAL CHARACTERISTICS (CONTINUOUS)**





# **\* PACKAGE OUTLINES**



Symbol	Dimensions in Millimeters			Dimensions in Inches			
	Min.	Nom.	Max.	Min.	Nom.	Max.	
Α	-	-	1.75	-	-	0.069	
A1	0	-	0.15	0	-	0.06	
A2	1.25	-	-	0.049	-	-	
С	0.1	0.2	0.25	0.0075	0.008	0.01	
D	4.7	4.9	5.1	0.185	0.193	0.2	
E	3.7	3.9	4.1	0.146	0.154	0.161	
Н	5.8	6	6.2	0.228	0.236	0.244	
L	0.4	-	1.27	0.015	-	0.05	
b	0.31	0.41	0.51	0.012	0.016	0.02	
е	1.27 BSC				0.050 BSC		
у	-	-	0.1	-	-	0.004	
X	-	2.34	-	-	0.092	-	
Y	-	2.34	-	-	0.092	-	
θ	00	-	<b>8</b> 0	00	-	80	

Mold flash shall not exceed 0.25mm per side

JEDEC outline: MS-012 BA